

# Product Change Notification - JAON-22LAXV706

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**Date:** 29 Jun 2015

**Product Category:** Memory; Analog (Linear & Mixed Signal) AND Interface; Radio Frequency Devices; 8-bit Microcontrollers

**Notification subject:** CCB 1656 and 1656.01 Initial Notice: Qualification of CuPdAu bond wire in selected products of the 120K and 121K wafer technologies available in 8L SOIC package at MMT assembly site.

**Notification text:**

## **PCN Status:**

Initial notification

## **Microchip Parts Affected:**

Please open the attachments found in the attachments field below labeled as PCN\_#\_Affected\_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

## **Description of Change:**

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 120K and 121K wafer technologies available in 8L SOIC package at MMT assembly site.

## **Pre Change:**

Palladium coated copper wire (PdCu)

## **Post Change:**

Palladium coated copper wire with gold flash (CuPdAu)

## **Impacts to Data Sheet:**

None

**Reason for Change:**

To improve manufacturability and qualify palladium coated copper with gold flash (CuPdAu) bond wire.

**Change Implementation Status:**

In Progress

**Estimated First Ship Date:**

October 20, 2015 (date code: 1543)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

**Markings to Distinguish Revised from Unrevised Devices:**

Traceability code

**Revision History:**

**June 29, 2015:** Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

**Attachment(s):** [PCN\\_JAON-22LAXV706\\_Qual\\_Plan.pdf](#) [PCN\\_JAON-22LAXV706\\_Affected\\_CPN.pdf](#) [PCN\\_JAON-22LAXV706\\_Affected\\_CPN.xls](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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PCN_JAON-22LAXV706
CATALOG_PART_NBR
24AA02/SNRVC
24AA02-I/SNRVC
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PIC12LC509AT-04I/SNG063



**MICROCHIP**

# **QUALIFICATION PLAN**

**PCN #: JAON-22LAXV706**

**Date:  
Jun. 18, 2015**

**Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 120K and 121K wafer technologies available in 8L SOIC package at MMT assembly site.**

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**Purpose:** \_\_\_\_\_ Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 120K and 121K wafer technologies available in 8L SOIC package at MMT assembly site.

**MP code:** \_\_\_\_\_ ABBS14C2XA00

**Part No.:** \_\_\_\_\_ MCP6402-E/SN

**BD No:** \_\_\_\_\_ BDM-000763 rev.B (Engineering BD)

**CCB No.:** \_\_\_\_\_ 1656 and 1656.01

**Package:**

**Type** \_\_\_\_\_ 8L SOIC

**Width or Size** \_\_\_\_\_ 150 mils

**Die thickness:** \_\_\_\_\_ 15 mils

**Die size:** \_\_\_\_\_ 32.2 x 50.4 mils

**Lead frame:**

**Paddle size:** \_\_\_\_\_ 90x90 mils

**Material** \_\_\_\_\_ CDA194

**Surface** \_\_\_\_\_ Bare Cu

**Process** \_\_\_\_\_ Stamped

**Lead Lock** \_\_\_\_\_ No

**Part Number** \_\_\_\_\_ 10100812

**Treatment** \_\_\_\_\_ BOT

**Wire:**

**Material** \_\_\_\_\_ CuPdAu

**Die Attach Epoxy:**

**Part Number** \_\_\_\_\_ 8390A

**Conductive** \_\_\_\_\_ Yes

**Mold Compound:** \_\_\_\_\_ G600V



Test Name	Conditions	Sample Size	Min. Qty of Spares per Lot (should be properly marked)	Qty of Lots	Total Units	Fail Accept Qty	Est. Dur. Days	Special Instructions
Wire Bond Pull - WBP	Mil. Std. 883-2011	5	0	1	5	0 fails after TC	5	30 bonds from a minimum of 5 devices.
Wire Bond Shear - WBS	CDF-AEC-Q100-001	5	0	1	5	0	5	30 bonds from a minimum of 5 devices.
External Visual	Mil. Std. 883-2009/2010	All devices prior to submission for qualification testing	0	3	ALL	0	5	
HTSL (High Temp Storage Life)	+175 C for 504 hours or 150°C for 1008 hrs. Electrical test pre and post stress at +25C and hot temp. (1 lot to be tested at 150C)	45	5	1	50	0	10	Must be in progress at time of package release to production, but completion is not required for release to production.
Preconditioning - Required for surface mount devices	+150°C Bake for 24 hours, moisture loading requirements per MSL level + 3X reflow at peak reflow temperature per Jedec-STD-020D for package type; Electrical test pre and post stress at +25°C. MSL1 260°C	231	15	3	738	0	15	Spares should be properly identified. 77 parts from each lot to be used for HAST, Autoclave, Temp Cycle test.
HAST	+130°C/85% RH for 96 hours. Electrical test pre and post stress at +25°C and hot temp. (1 lot to be tested at 150C)	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Unbiased HAST	+130°C/85% RH for 96 hrs. Electrical test pre and post stress at +25°C.	77	5	3	246	0	10	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.
Temp Cycle	-65°C to +150°C for 500 cycles. Electrical test pre and post stress at hot temp; 3 gram force WBP, on 5 devices from 1 lot, Test by following readpoint TC 500. (1 lot to be tested at 150C)	77	5	3	246	0	15	Spares should be properly identified. Use the parts which have gone through Pre-conditioning.